

NOTES, UNLESS OTHERWISE SPECIFIED:

1. The netname "VCC" represents connection to the +2.5V power plane.
2. The netname "GND" represents connection to the ground plane.



COMPUTER GENERATED DRAWING - DO NOT REVISE MANUALLY

REVISIONS

REV	DESCRIPTION	DATE	APPROVED
A	ECO 2136070: Initial Release	9/18/2013	NG

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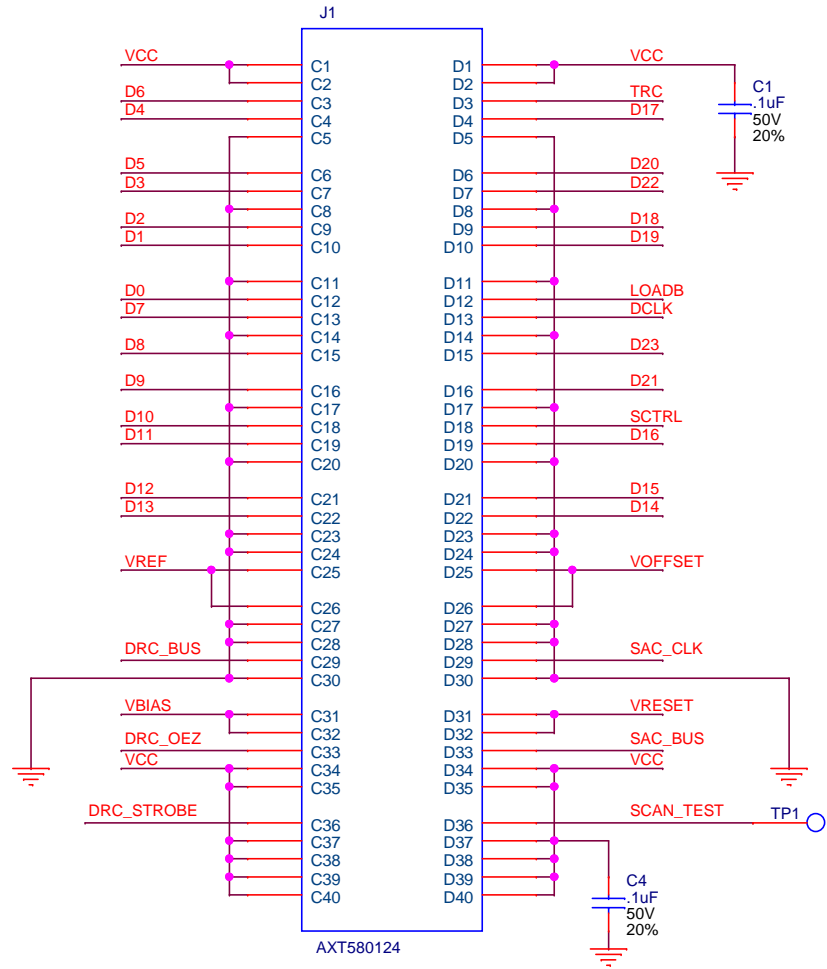
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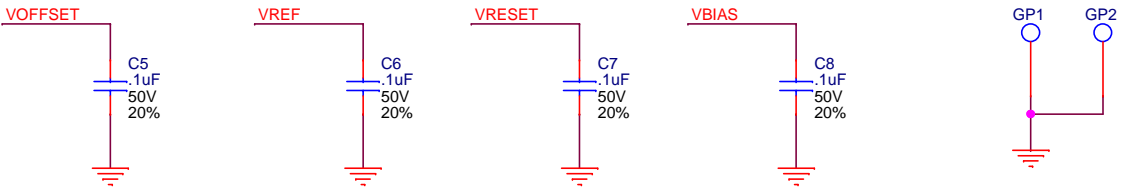
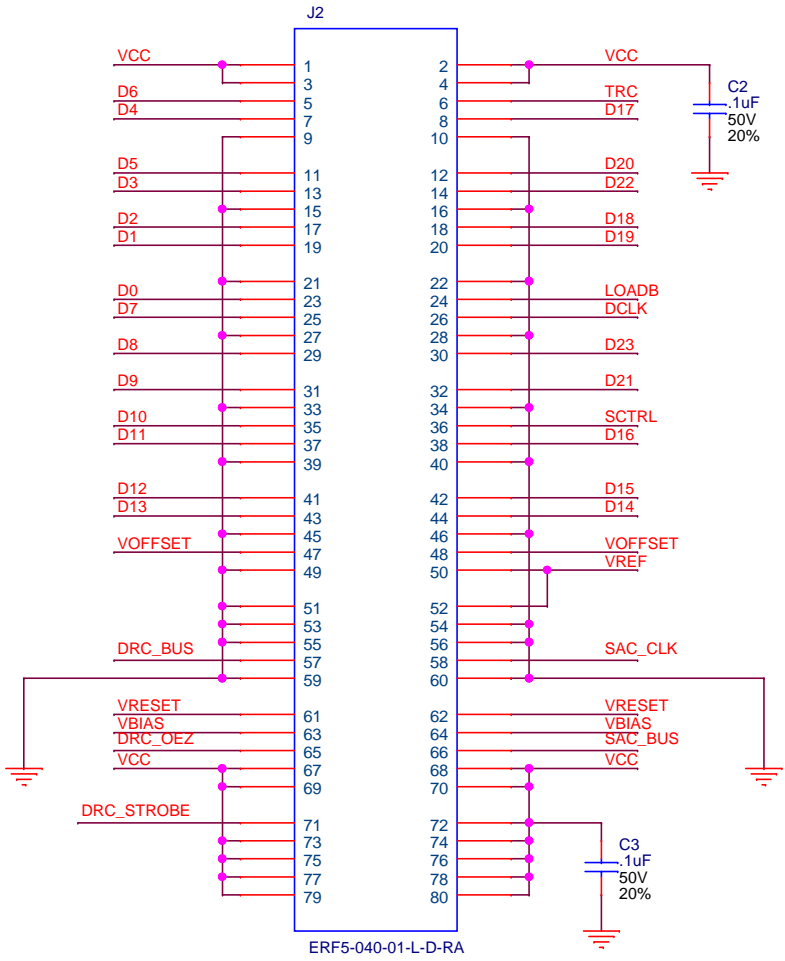
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		ENGR A. NG	09/18/2013			
		APVD Joe Siddall				
		MFG		TITLE  ESD, NIRscan s241 DMD Board		
	0314CP	QA				
NEXT ASSY	USED ON					
APPLICATION		SW Allegro Design Entry 16.6		A3	DRAWING NO 2513466	REV A
				SCALE	SHEET 1 of 4	

5		4		3		2		1			
D										D	
C										C	
B										B	
A										A	

DMD Connector



Samtec RA



Revision History

Rev. A: ECO 2136070: Initial Release ~ 9/18/2013

TEXAS INSTRUMENTS

DWN  
A. Ng

DATE  
09/18/2013

ISSUE DATE  
09/18/2013

A3

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2513466

REV  
A

SCALE SHEET 4 OF 4